

Low Loss FPC (GHz band • Microstrip Line)

Characteristics of each type/layer structure

【 Under development : PTFE-based and Low dielectric cover-layer 】

- PTFE-based FPC of 100μm thickness
- Insulation cover with low dielectric cover-layer
- This is Structure of most low-loss

Product image



【 LCP-based and Low dielectric cover-layer 】

- LCP-based FPC of 50μm thickness
- Insulation cover with low dielectric cover-layer
- This low-loss FPC is possible mass production

Product image



【 LCP-based and General cover-layer 】

- LCP-based FPC of 50μm thickness
- Bending resistance and heat resistance is excellent in the range of LCP-based

Product image



Thickness [μm]

12	Polyimide
25	Low dielectric adhesive
RF line	28 Conductor
100	Poly tetra fluoro ethylene
GND	28 Conductor
25	Low dielectric adhesive
12	Polyimide

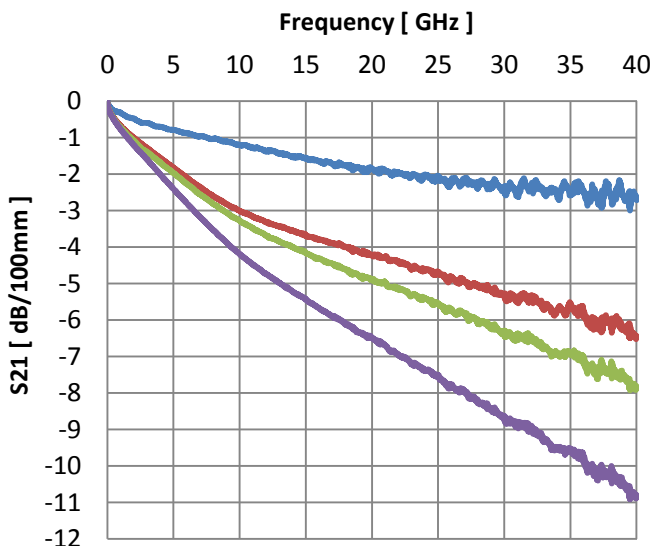
Thickness [μm]

12	Polyimide
25	Low dielectric adhesive
RF line	28 Conductor
50	Liquid crystal polymer
GND	28 Conductor
25	Low dielectric adhesive
12	Polyimide

Thickness [μm]

12	Polyimide
25	Adhesive
RF line	28 Conductor
50	Liquid crystal polymer
GND	28 Conductor
25	Adhesive
12	Polyimide

S21 measurement results



- In development : PTFE-based and Low dielectric cover-layer
- LCP-based and low dielectric cover-layer
- LCP-based and General cover-layer
- Reference : PI-based and General cover-layer

【 Evaluation sample specification 】

Impedance : single 50 ohm

Signal length : 100mm

Measurement probe : GSG250um pitch

Note, Data are measured values, it is not a guaranteed value